

2019 IEEE INTERNATIONAL SYMPOSIUM ON ELECTROMAGNETIC COMPATIBILITY, SIGNAL & POWER INTEGRITY





EMC+SIPI
NEW ORLEANS, LOUISIANA

2019
JULY 22-26

**2019 IEEE INTERNATIONAL SYMPOSIUM ON
ELECTROMAGNETIC COMPATIBILITY, SIGNAL & POWER INTEGRITY**

Introduction

- **Wang Lin Biao** | ID CD-EE
 - 2012 ~ 2018: High Speed Engineer
 - 2018 ~ 2019: EMC Engineer
- **Academic:** B. Eng, M.Sc, Ph.D in EEE from Nanyang Technological University
- **Additional responsibility:** Location Spokesperson (Continental Automotive Singapore), Secretary for IEEE EMC Society (Singapore)
- **Highlights**
 - Received Expert Title in 2016. Promoted from L1 to L2 in 2018.
 - Speaker in events:
 - 2014 International Symposium in Integrated Circuits, 2016 CST Workshop, 2016 Asia Pacific EMC Conference 2017 IEEE EMC MasterClass, 2017 Innovation Week Tech Talk, 2018 PCB Design And Simulation Workshop
 - 2017 Regional Expert Day, 2017 Rohde & Schwarz Technology Symposium, 2018 Simulia ASEAN User Conference, 2018 Keysight Measurement Forum.
 - 2018 APEMC with 1 technical presentation and 1 short lecture in PCB design for EMC

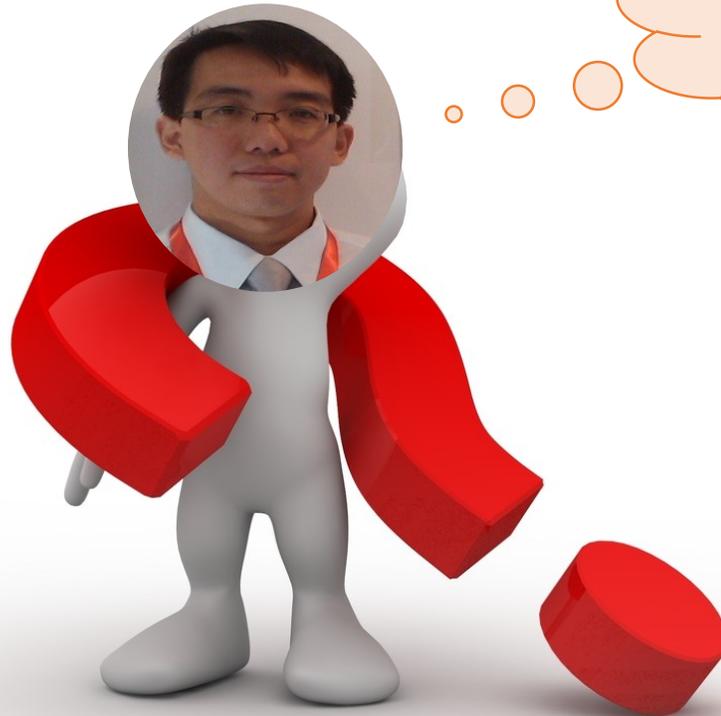




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Bachelor degree or
equivalent within the
last 15 years





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